



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **TOKUDA, Kazuhiko**

Group Art Unit: **3729**

Serial No.: **09/928,441**

Examiner: **Rick Kiltae Chang**

Filed: **August 14, 2001**

P.T.O. Confirmation No.: 8352

For: **A METHOD OF FORMING WIRING LINES ON A BOARD
TO FORM A CIRCUIT BOARD**

Preliminary Remarks

MAILSTOP Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

April 24, 2007

Sir:

In view of filing of the Request for Continued (RCE) on even date herewith, Applicant respectfully requests that the Examiner reconsider and remove the rejection of Claims 37 and 38.

Claims 37 and 38 read as follows:

Claim 37. A method of forming a plurality of wiring lines on conductive material on a board having a core layer to form a printed circuit board, comprising:

- (a) forming said plurality of wiring lines on a surface of said core layer, having first and second portions, the plurality of wiring lines formed on said surface of said core having side walls of a uniform thickness in height relative to said surface of said core layer; and